

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3477	(silicon wafer layer stack) with magnet\$7 with anneal\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 07:23
L2	58	1 and ((magnet\$7 near5 anneal\$5) with wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 08:10
L3	4	2 and (anneal\$5 with (lamp laser flashlight rta))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 07:25
L4	268	(magnetoresist\$5 wafer) with magnet\$7 with anneal\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 07:24
L5	11	4 and (anneal\$5 with (lamp laser flashlight rta))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 07:57
L6	1	("6649423").PN.	USPAT; USOCR	OR	OFF	2005/08/28 07:57
L11	11061	spot near2 spot	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 08:12
L12	303338	line near2 line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 08:12
L13	313209	11 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 08:12
L14	209	13 with anneal\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 08:24

L15	3	13 with anneal\$5 with wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 08:13
L16	209	14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 08:37
L17	7	(13 with anneal\$5) and (anneal\$5 with wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 08:25
L18	1987	wafer with (cooled cooling cool) with (helium argon nitrogen vacuum)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 08:38
L19	16	wafer with (cooled cooling cool) with (helium argon nitrogen vacuum) with (anneal\$ near5 temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 09:28
L20	4441	219/121.6,121.65,121.66,121.84, 121.85.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 09:28
L21	1	20 and (wafer with anneal\$5 with magnet\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 09:29
L22	1	20 and (wafer with anneal\$5) and (wafer with magnet\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 09:29
L23	7	20 and ((silicon layer stack wafer) with anneal\$5) and ((silicon layer stack wafer) with magnet\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/28 09:30